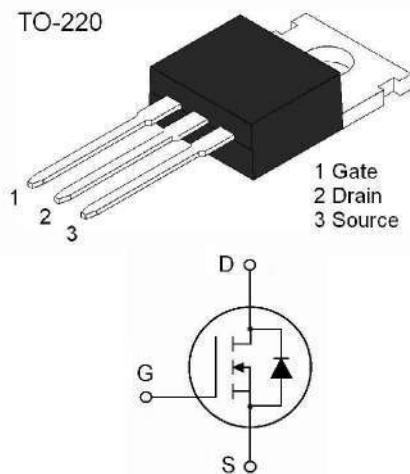


## TO-220 Plastic-Encapsulate MOSFETS

N-Channel mode Power MOSFET

### Features

- $V_{DS}$  200V
- $I_D$  9A
- $R_{DS(ON)}$  ( $V_{GS} = 10V$ )  $< 0.4\Omega$
- High switching speed
- Improved dv/dt capability



**Absolute Maximum Ratings** ( $T_A = 25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Ratings	Units
Gate-Drain Voltage	$V_{DSS}$	200	V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Continuous Drain Current  Pulsed (Note 1)	$I_D$	9	A
	$I_{DM}$	36	
Avalanche Current (Note 1)	$I_{AR}$	9	A
Single Pulsed Avalanche Energy (Note 2)	$E_{AS}$	160	mJ
Repetitive Avalanche Energy (Note 1)	$E_{AR}$	7.2	mJ
dv/dtPeak Diode Recovery dv/dt (Note 3)	dv/dt	5.5	V/ns
Power Dissipation	$P_D$	72	W
Junction Temperature	$T_J$	150	$^\circ C$
Storage Temperature	$T_{STG}$	-55~155	$^\circ C$

### Thermal Characteristic

Parameter	Symbol	Value	Units
Thermal Resistance, Junction-Case	$R_{\theta JC}$	1.74	$^\circ C/W$
Thermal Resistance, Junction-Ambient	$R_{\theta JA}$	62.5	$^\circ C/W$

## Typical Characteristics

**Electrical Characteristics** ( $T_j = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Conditions	Min.	Typ	Max.	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	200			V
Breakdown Voltage Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	$I_{\text{D}}=1\text{mA}$ , Referenced to $25^\circ\text{C}$		0.2		$\text{V}/^\circ\text{C}$
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=200\text{V}, V_{\text{GS}}=0\text{V}$		10		$\mu\text{A}$
		$V_{\text{DS}}=160\text{V}, V_{\text{GS}}=0\text{V}$ $T_c=125^\circ\text{C}$			100	
Gate Leakage Current	$I_{\text{GSS}}$	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 30\text{V}$			$\pm 100$	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.0		4.0	V
Drain-source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=4.5\text{A}$			0.18	$\Omega$
Forward Transconductance(Note4)	$g_{\text{FS}}$	$V_{\text{DS}}=40\text{V}, I_{\text{D}}=4.5\text{A}$		7.05		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$		550		pF
Output Capacitance	$C_{\text{oss}}$			85		
Reverse Transfer Capacitance	$C_{\text{rss}}$			22		
<b>Switching Characteristics</b> )						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=100\text{V}, I_{\text{D}}=9\text{A}$ $R_G=25\Omega$ (Note4, 5)		11		ns
Turn-on Rise Time	$t_r$			70		
Turn-Off elay Time	$t_{\text{d(off)}}$			60		
Turn-Off Fall	$t_f$			65		
Total Gate Charge	$Q_g$	$V_{\text{DS}}=160\text{V}, I_{\text{D}}=9\text{A}$ $V_{\text{GS}}=10\text{V}$ (Note 4, 5)		22		nC
Gate-Source Charge	$Q_{\text{gs}}$			3.6		
Gate-Drain Charge	$Q_{\text{gd}}$			10.2		
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=9\text{A}$			1.5	V
Diode Forward Current	$I_{\text{S}}$	-			9	A
Pulsed Diode Forward Current	$I_{\text{SM}}$	-			36	A
Reverse Recovery Time	$t_{\text{rr}}$	$I_{\text{S}}=9\text{A}, V_{\text{GS}}=0\text{V}$ $dI/dt=100\text{A}/\mu\text{s}$ (Note 4)		140		ns
Reverse Recovery Charge	$Q_{\text{rr}}$			0.87		$\mu\text{C}$

Note: 1. Repetitive Rating : Pulse width limited by maximum junction temperature

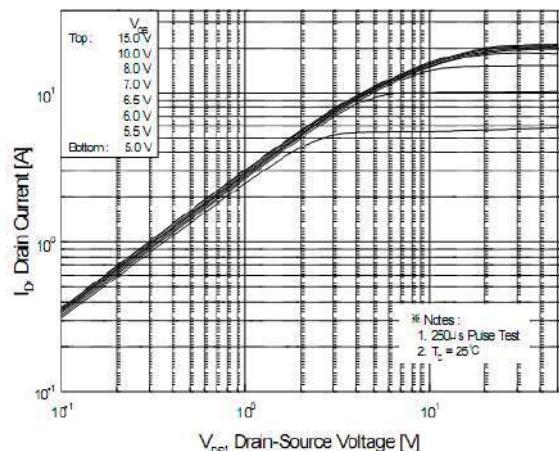
2.  $L = 13\text{mH}, I_{\text{AS}} = 9\text{A}, V_{\text{DD}} \leq \text{BV}_{\text{DSS}}$ , Starting  $T_j = 25^\circ\text{C}$

3.  $I_{\text{SD}} \leq 9\text{A}, di/dt \leq 300\text{A}/\mu\text{s}, V_{\text{DD}} \leq \text{BV}_{\text{DSS}}$ , Starting  $T_j = 25^\circ\text{C}$

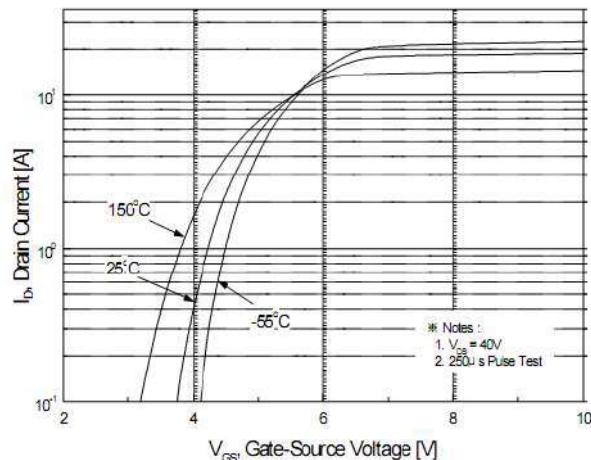
4. Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$

5. Essentially independent of operating temperature

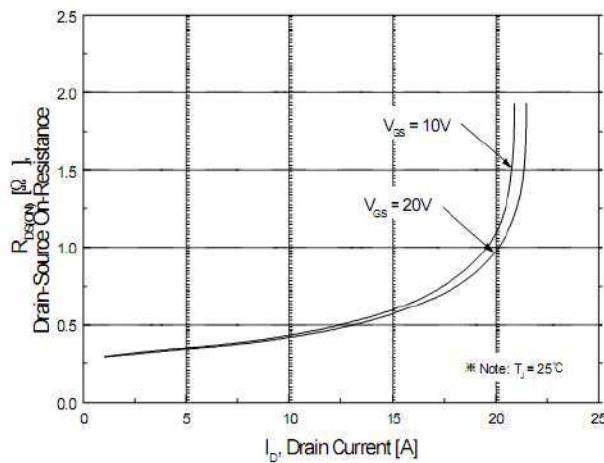
## Typical Characteristics



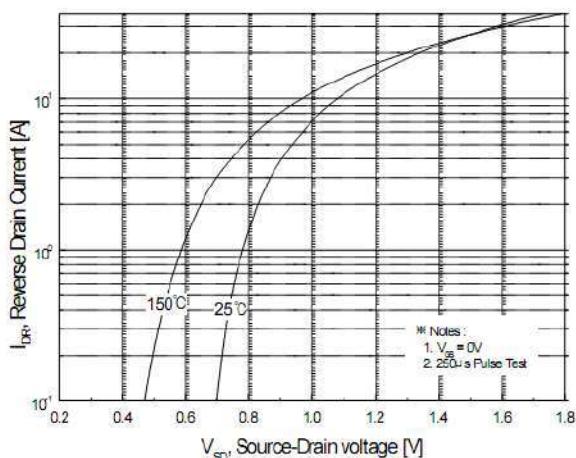
**Figure 1. Typical Output Characteristics**



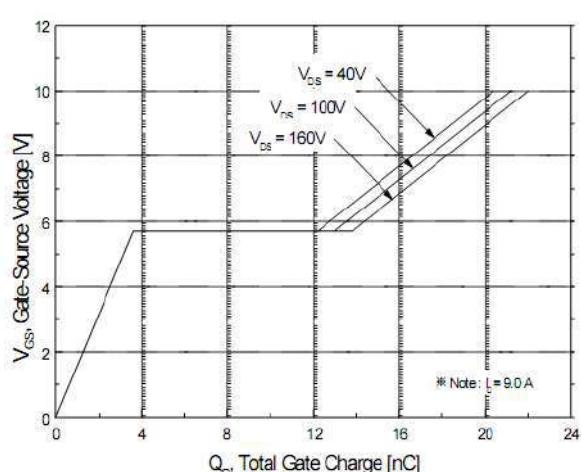
**Figure 2. Transfer Characteristics**



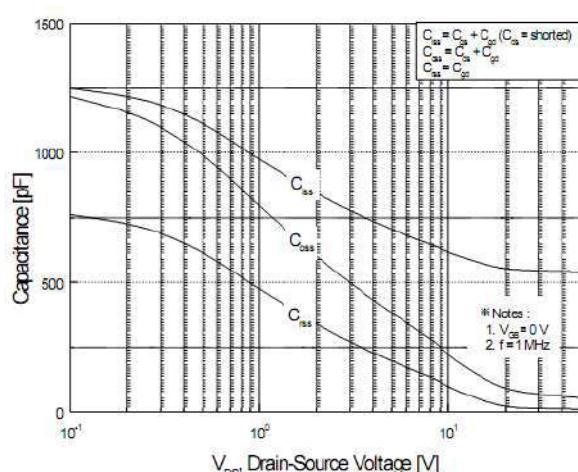
**Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage**



**Figure 4. Body Diode Characteristics**

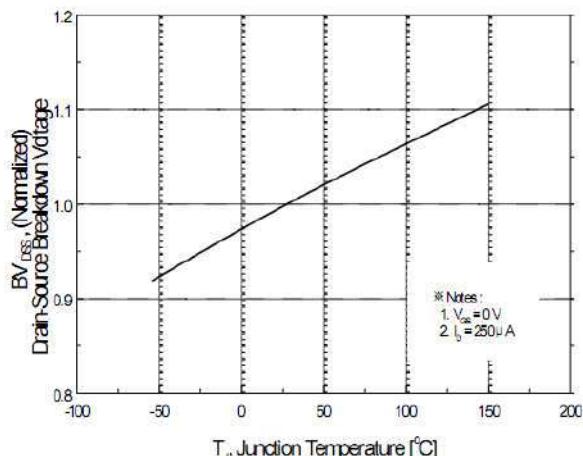


**Figure 5. Drain to Source ON Resistance vs Drain Current**

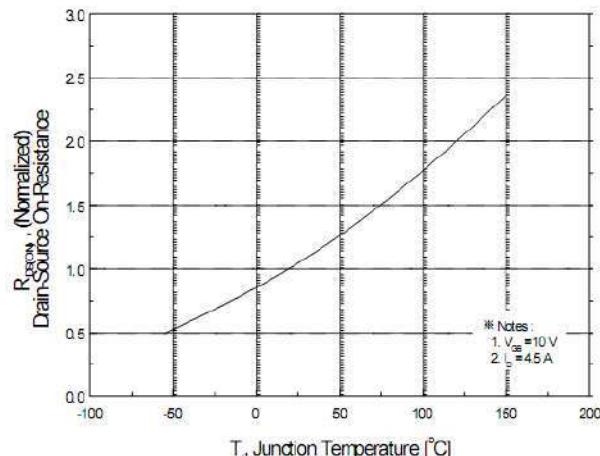


**Figure 6. Gate Charge Characteristics**

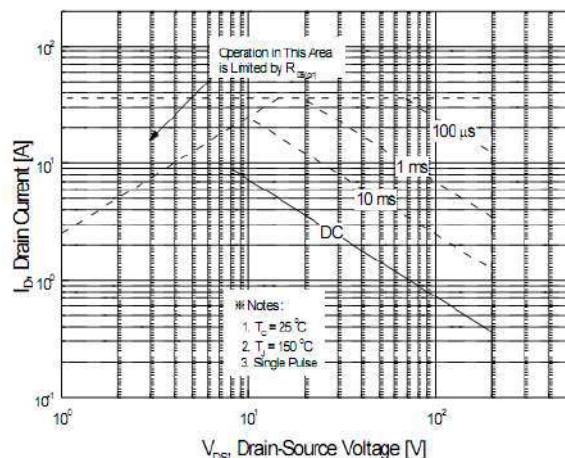
### Typical Characteristics (Continued)



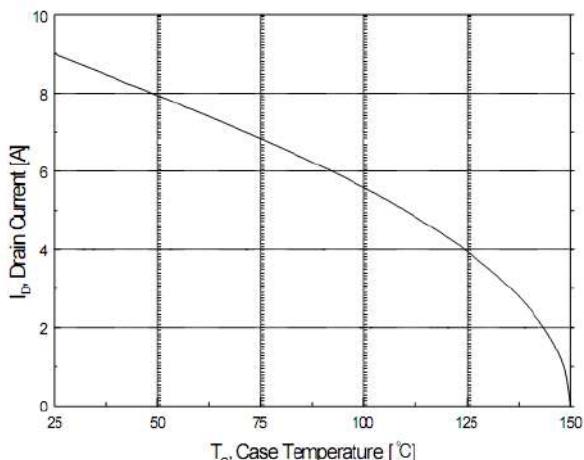
**Figure 7. Breakdown Voltage Variation  
vs Temperature**



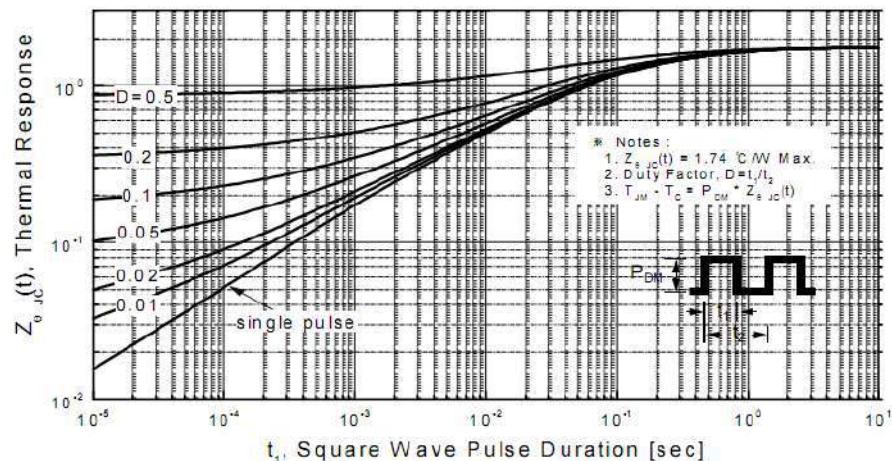
**Figure 8. On-Resistance Variation  
vs Temperature**



**Figure 9. Safe Operating Area**



**Figure 10. Maximum Drain Current  
vs Case Temperature**



**Figure 11. Transient Thermal Response Curve**

## Test Circuits and waveforms

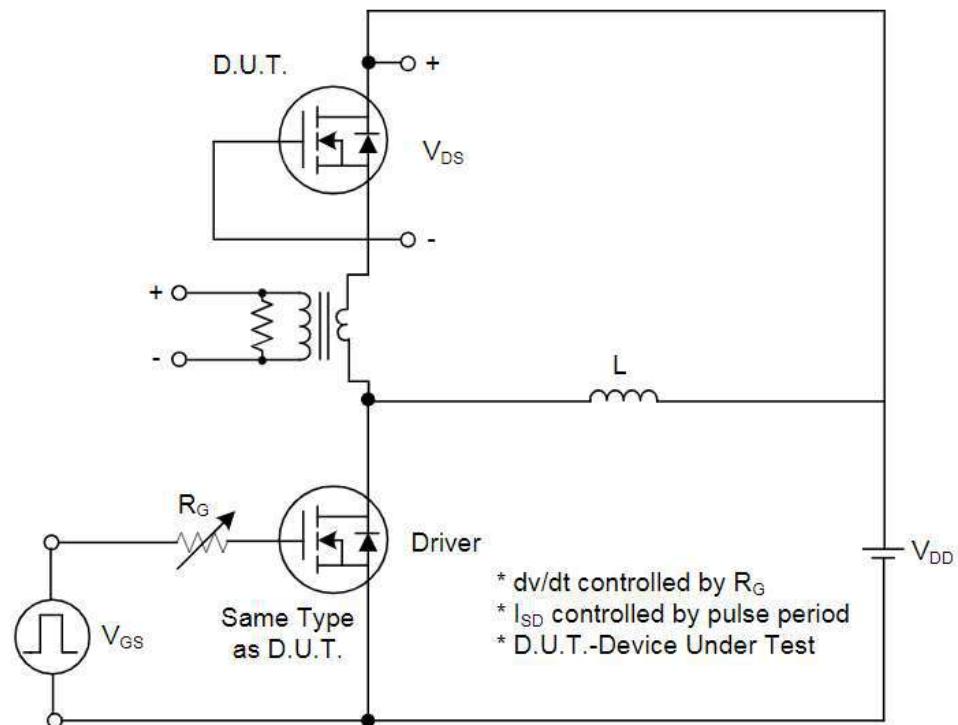


Figure 12. Peak Diode Recovery  $dv/dt$  Test Circuit

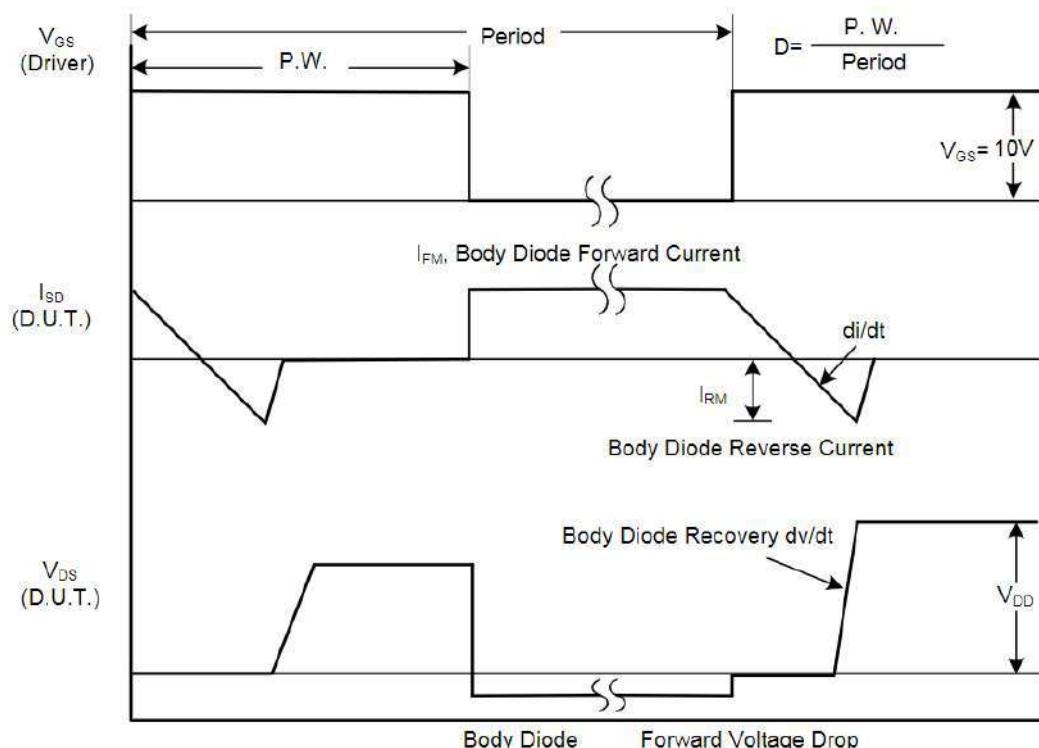


Figure 13. Peak Diode Recovery  $dv/dt$  Waveforms

### Test Circuits and waveforms

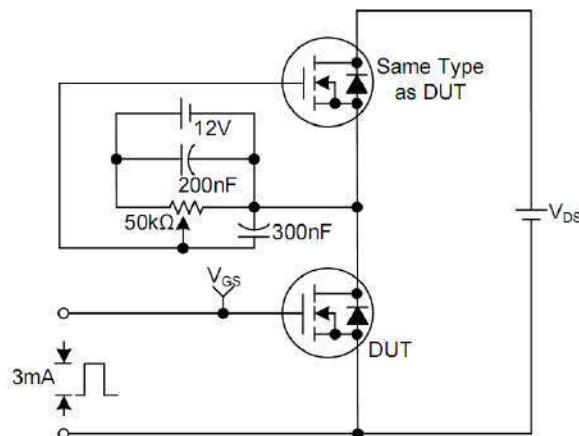


Figure 14. Gate Charge Test Circuit

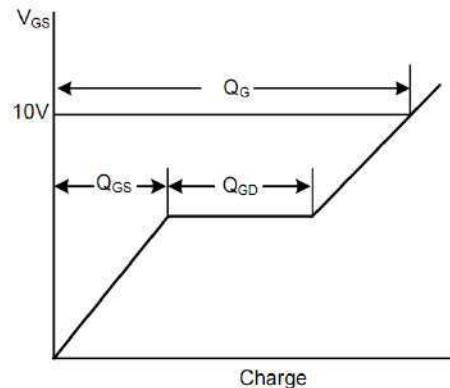


Figure 15. Gate Charge Waveforms

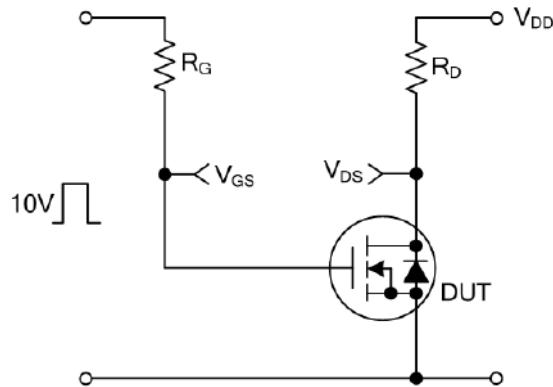


Figure 16. Resistive Switching Circuit

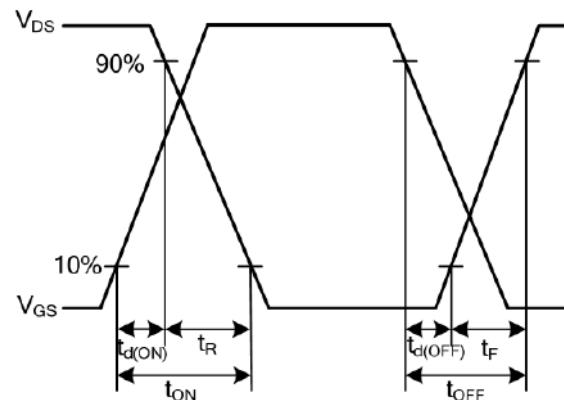


Figure 17. Resistive Switching Waveforms

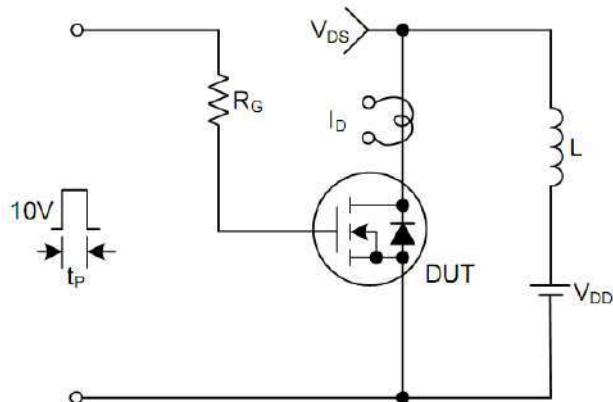


Figure 18. Unclamped Inductive Switching Test Circuit

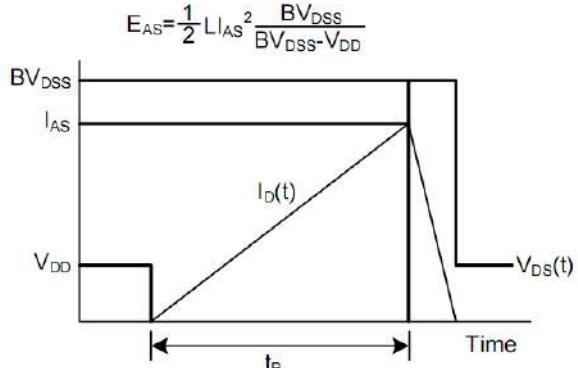


Figure 19. Unclamped Inductive Switching Waveforms

## TO-220 Package Outline Dimensions

### Package Dimensions

Dim	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.34	4.67	0.171	0.184
A1	2.52	2.82	0.099	0.111
b	0.71	0.91	0.028	0.036
b1	1.17	1.37	0.046	0.054
c	0.30	0.50	0.012	0.020
c1	1.17	1.37	0.046	0.054
D	9.90	10.20	0.390	0.402
E	8.50	8.90	0.335	0.350
E1	12.00	12.50	0.472	0.492
e	2.44	2.64	0.096	0.104
e1	4.88	5.28	0.192	0.208
F	2.60	2.80	0.102	0.110
L	13.20	13.80	0.520	0.543
L1	3.80	4.20	0.150	0.165
Φ	3.60	3.96	0.142	0.156